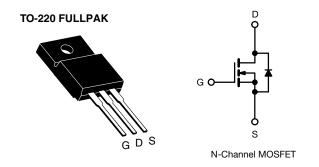


# **E Series Power MOSFET**

| PRODUCT SUMMARY                            |                              |  |  |  |
|--|------------------------------|--|--|--|
| V <sub>DS</sub> (V) at T <sub>J</sub> max. | 650                          |  |  |  |
| R <sub>DS(on)</sub> typ. (Ω) at 25 °C      | V <sub>GS</sub> = 10 V 0.082 |  |  |  |
| Q <sub>g</sub> max. (nC)                   | 132                          |  |  |  |
| Q <sub>gs</sub> (nC)                       | 22                           |  |  |  |
| Q <sub>gd</sub> (nC)                       | 46                           |  |  |  |
| Configuration                              | Single                       |  |  |  |



### **FEATURES**

• A specific on resistance (m $\Omega$ -cm $^2$ ) reduction of 25 %



COMPLIANT

HALOGEN

**FREE** 

- $\bullet$  Low figure-of-merit (FOM)  $R_{on}\:x\:Q_g$
- Low input capacitance (C<sub>iss</sub>)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

### **APPLICATIONS**

- Power factor correction power supplies (PFC)
- · Hard switching PWM stages
- Computing
  - Switch mode power supplies (SMPS)
- Lighting
  - Light emitting diode (LED)
  - High intensity discharge (HID)
- Telecom
  - Server power supplies
- · Renewable energy
  - Photovoltaic inverters
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Uniterruptable power supplies

| ORDERING INFORMATION            |                |
|---------------------------------|----------------|
| Package                         | TO-220 FULLPAK |
| Lead (Pb)-free and Halogen-free | SiHF35N60E-GE3 |

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>   | = 25 °C, unl   | ess otherwis           | se noted)                         |             |       |
|--|--|------------------------|-----------------------------------|-------------|-------|
| PARAMETER  |  |                        | SYMBOL                            | LIMIT       | UNIT  |
| Drain-Source Voltage   |  |                        | $V_{DS}$                          | 600         | V     |
| Gate-Source Voltage  |  |                        | $V_{GS}$                          | ± 30        | v     |
| Continuous Drain Current /T 150 °C\ e  | \/ at 10.\/  | T <sub>C</sub> = 25 °C |                                   | 32          |       |
| Continuous Drain Current ( $T_J = 150 ^{\circ}\text{C}$ ) e $V_{GS}$ at 10 V $T_C = 25 ^{\circ}\text{C}$ |  | I <sub>D</sub>         | 20                                | Α           |       |
| Pulsed Drain Current <sup>a</sup>  |  |                        | I <sub>DM</sub>                   | 80          |       |
| Linear Derating Factor   |  |                        |                                   | 0.31        | W/°C  |
| Single Pulse Avalanche Energy b  |  |                        | E <sub>AS</sub>                   | 691         | mJ    |
| Maximum Power Dissipation  |  |                        | $P_{D}$                           | 39          | W     |
| Operating Junction and Storage Temperature Range   |  |                        | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C    |
| Drain-Source Voltage Slope T <sub>J</sub> = 125 °C   |  | dV/dt                  | 57                                | V/ns        |       |
| Reverse Diode dV/dt <sup>d</sup>   |  |                        | av/at                             | 31          | V/IIS |
| Soldering Recommendations (Peak temperature) c   | Soldering Recommendations (Peak temperature) <sup>c</sup> For 10 s |                        |                                   | 300         | °C    |
| Mounting Torque M3 screw   |  |                        |                                   | 0.6         | Nm    |

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD} = 140 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 28.2 \, \text{mH}$ ,  $R_g = 25 \, \Omega$ ,  $I_{AS} = 7 \, \text{A}$ .
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , dI/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C.
- e. Limited by maximum junction temperature.



# Vishay Siliconix

| THERMAL RESISTANCE RATINGS       |            |      |      |      |
|----------------------------------|------------|------|------|------|
| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient      | $R_{thJA}$ | =    | 65   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$ | -    | 3.2  | C/VV |

| PARAMETER  | SYMBOL                | TEST CONDITIONS  |   | MIN. | TYP.  | MAX.  | UNIT |
|--|-----------------------|--|---|------|-------|-------|------|
| Static   |                       |  |   | l    | l .   | •     |      |
| Drain-Source Breakdown Voltage                             | V <sub>DS</sub>       | V <sub>GS</sub> :  | = 0 V, I <sub>D</sub> = 250 μA                    | 600  | -     | -     | V    |
| V <sub>DS</sub> Temperature Coefficient                    | $\Delta V_{DS}/T_{J}$ | Referenc   | e to 25 °C, I <sub>D</sub> = 1 mA                 | -    | 0.70  | -     | V/°C |
| Gate-Source Threshold Voltage (N)                          | V <sub>GS(th)</sub>   | V <sub>DS</sub> =  | = V <sub>GS</sub> , I <sub>D</sub> = 250 μA       | 2    | -     | 4     | ٧    |
| Cata Carriaga Laghaga                                      | ,                     |  | V <sub>GS</sub> = ± 20 V                          | -    | -     | ± 100 | nA   |
| Gate-Source Leakage  | I <sub>GSS</sub>      |  | $V_{GS} = \pm 30 \text{ V}$                       | -    | -     | ± 1   | μΑ   |
| Zaus Cata Valta as Busin Comment                           |                       | V <sub>DS</sub> =  | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V    |      | -     | 1     |      |
| Zero Gate Voltage Drain Current                            | I <sub>DSS</sub>      | V <sub>DS</sub> = 480 \  | /, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C | -    | -     | 25    | μA   |
| Drain-Source On-State Resistance                           | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V   | I <sub>D</sub> = 17 A                             | -    | 0.082 | 0.094 | Ω    |
| Forward Transconductance                                   | 9 <sub>fs</sub>       | $V_{DS}$   | = 30 V, I <sub>D</sub> = 17 A                     | -    | 13    | -     | S    |
| Dynamic  |                       |  |   |      |       |       |      |
| Input Capacitance  | C <sub>iss</sub>      |  | $V_{GS} = 0 V$ ,                                  | -    | 2760  | -     |      |
| Output Capacitance   | C <sub>oss</sub>      |  | $V_{DS} = 100 \text{ V},$                         | -    | 118   | -     |      |
| Reverse Transfer Capacitance                               | C <sub>rss</sub>      | 1  | f = 1 MHz   | -    | 5     | -     |      |
| Effective Output Capacitance, Energy Related <sup>a</sup>  | C <sub>o(er)</sub>    | ٧, ٥١  | /+- 400 V V 0 V                                   | -    | 118   | -     | pF   |
| Effective Output Capacitance, Time<br>Related <sup>b</sup> | C <sub>o(tr)</sub>    | $V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$       |   | -    | 429   | -     |      |
| Total Gate Charge  | Qg                    |  |   | -    | 88    | 132   |      |
| Gate-Source Charge   | Q <sub>gs</sub>       | V <sub>GS</sub> = 10 V   | $I_D = 17 A, V_{DS} = 480 V$                      | -    | 22    | -     | nC   |
| Gate-Drain Charge  | Q <sub>gd</sub>       |  |   | -    | 46    | -     |      |
| Turn-On Delay Time   | t <sub>d(on)</sub>    |  |   | -    | 29    | 58    |      |
| Rise Time  | t <sub>r</sub>        | V <sub>DD</sub> -  | = 480 V, I <sub>D</sub> = 17 A,                   | -    | 61    | 92    |      |
| Turn-Off Delay Time  | t <sub>d(off)</sub>   |  | = 10 V, $R_q = 9.1 \Omega$                        | -    | 78    | 117   | ns   |
| Fall Time  | t <sub>f</sub>        |  | v   | -    | 32    | 64    |      |
| Gate Input Resistance                                      | R <sub>g</sub>        | f = 1  | MHz, open drain                                   | 0.25 | 0.5   | 1     | Ω    |
| Drain-Source Body Diode Characteristic                     | s                     |  |   |      |       |       |      |
| Continuous Source-Drain Diode Current                      | I <sub>S</sub>        | MOSFET sym showing the   | bol   | -    | -     | 32    | _    |
| Pulsed Diode Forward Current                               | I <sub>SM</sub>       | integral reverse p - n junction diode                                |   | -    | -     | 80    | A    |
| Diode Forward Voltage                                      | V <sub>SD</sub>       | T <sub>J</sub> = 25 °C, I <sub>S</sub> = 17 A, V <sub>GS</sub> = 0 V |   | -    | 0.9   | 1.2   | V    |
| Reverse Recovery Time                                      | t <sub>rr</sub>       |  |   | -    | 455   | 910   | ns   |
| Reverse Recovery Charge                                    | Q <sub>rr</sub>       |  | 5 °C, I <sub>F</sub> = I <sub>S</sub> = 17 A,     | -    | 8     | 16    | μC   |
| Reverse Recovery Current                                   | I <sub>RRM</sub>      | ai/at =  | 100 A/ $\mu$ s, V <sub>R</sub> = 25 V             | -    | 30    | -     | A    |

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

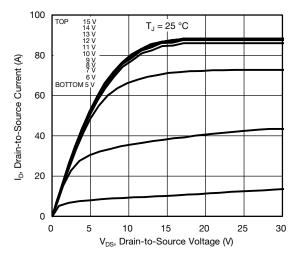


Fig. 1 - Typical Output Characteristics

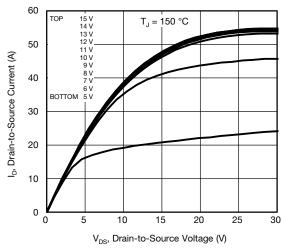


Fig. 2 - Typical Output Characteristics

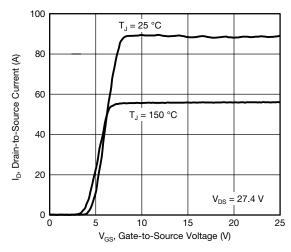


Fig. 3 - Typical Transfer Characteristics

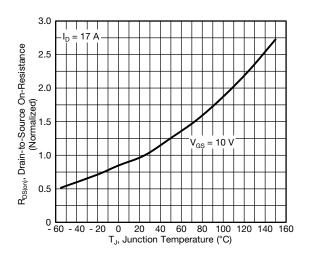


Fig. 4 - Normalized On-Resistance vs. Temperature

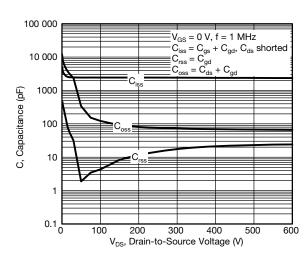


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

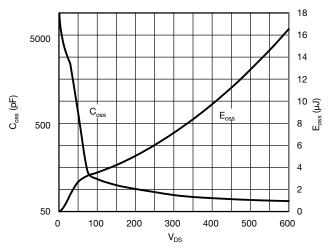


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



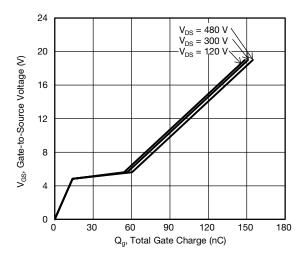


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

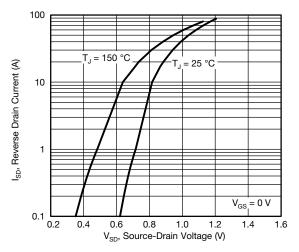


Fig. 8 - Typical Source-Drain Diode Forward Voltage

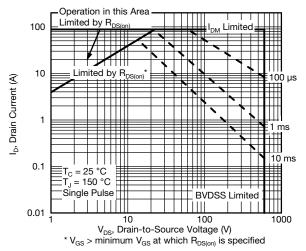


Fig. 9 - Maximum Safe Operating Area

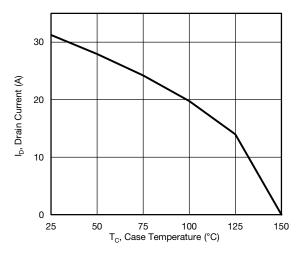


Fig. 10 - Maximum Drain Current vs. Case Temperature

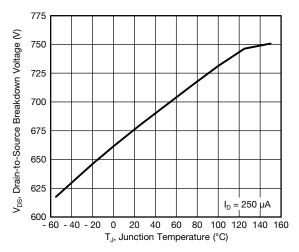


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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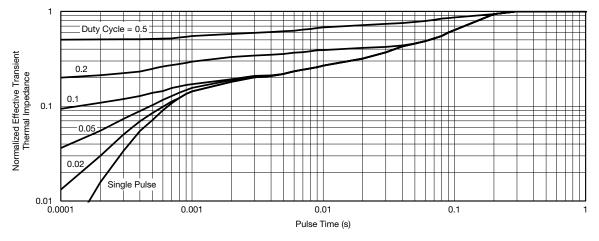


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

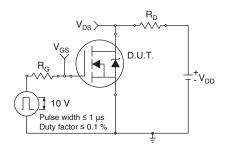


Fig. 13 - Switching Time Test Circuit

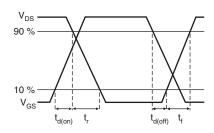


Fig. 14 - Switching Time Waveforms

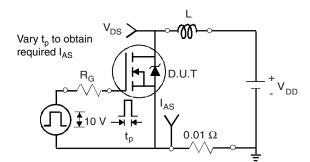


Fig. 15 - Unclamped Inductive Test Circuit

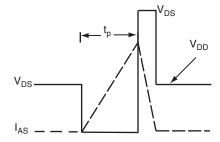


Fig. 16 - Unclamped Inductive Waveforms

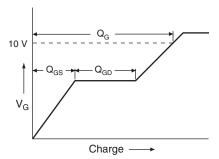


Fig. 17 - Basic Gate Charge Waveform

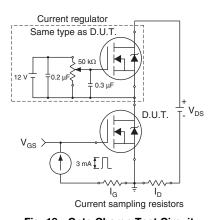
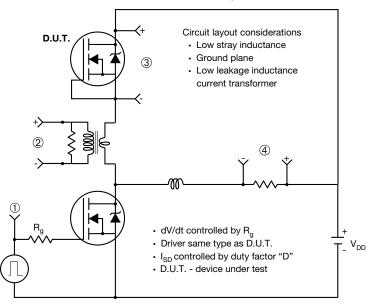


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



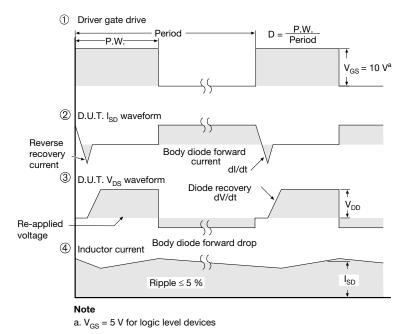


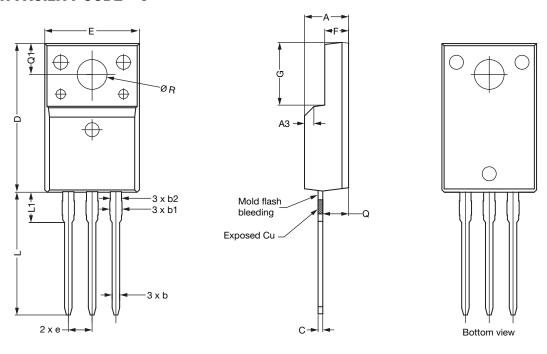
Fig. 19 - For N-Channel

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Vishay Siliconix

# **TO-220 FULLPAK (High Voltage)**

## **OPTION 1: FACILITY CODE = 9**

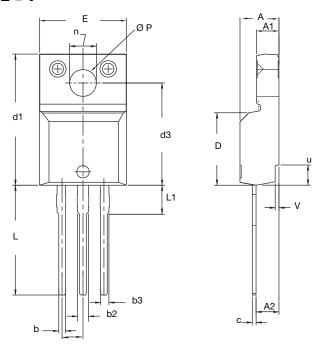


|      |       | MILLIMETERS |       |
|------|-------|-------------|-------|
| DIM. | MIN.  | NOM.        | MAX.  |
| Α    | 4.60  | 4.70        | 4.80  |
| b    | 0.70  | 0.80        | 0.91  |
| b1   | 1.20  | 1.30        | 1.47  |
| b2   | 1.10  | 1.20        | 1.30  |
| С    | 0.45  | 0.50        | 0.63  |
| D    | 15.80 | 15.87       | 15.97 |
| е    |       | 2.54 BSC    |       |
| E    | 10.00 | 10.10       | 10.30 |
| F    | 2.44  | 2.54        | 2.64  |
| G    | 6.50  | 6.70        | 6.90  |
| L    | 12.90 | 13.10       | 13.30 |
| L1   | 3.13  | 3.23        | 3.33  |
| Q    | 2.65  | 2.75        | 2.85  |
| Q1   | 3.20  | 3.30        | 3.40  |
| ØR   | 3.08  | 3.18        | 3.28  |

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet  $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



## **OPTION 2: FACILITY CODE = Y**



|      | MILLIMETERS |        | INCHES    |       |  |
|------|-------------|--------|-----------|-------|--|
| DIM. | MIN.        | MAX.   | MIN.      | MAX.  |  |
| Α    | 4.570       | 4.830  | 0.180     | 0.190 |  |
| A1   | 2.570       | 2.830  | 0.101     | 0.111 |  |
| A2   | 2.510       | 2.850  | 0.099     | 0.112 |  |
| b    | 0.622       | 0.890  | 0.024     | 0.035 |  |
| b2   | 1.229       | 1.400  | 0.048     | 0.055 |  |
| b3   | 1.229       | 1.400  | 0.048     | 0.055 |  |
| С    | 0.440       | 0.629  | 0.017     | 0.025 |  |
| D    | 8.650       | 9.800  | 0.341     | 0.386 |  |
| d1   | 15.88       | 16.120 | 0.622     | 0.635 |  |
| d3   | 12.300      | 12.920 | 0.484     | 0.509 |  |
| Е    | 10.360      | 10.630 | 0.408     | 0.419 |  |
| е    | 2.54        | BSC    | 0.100 BSC |       |  |
| L    | 13.200      | 13.730 | 0.520     | 0.541 |  |
| L1   | 3.100       | 3.500  | 0.122     | 0.138 |  |
| n    | 6.050       | 6.150  | 0.238     | 0.242 |  |
| ØΡ   | 3.050       | 3.450  | 0.120     | 0.136 |  |
| u    | 2.400       | 2.500  | 0.094     | 0.098 |  |
| V    | 0.400       | 0.500  | 0.016     | 0.020 |  |

ECN: E19-0180-Rev. D, 08-Apr-2019

DWG: 5972

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet  $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



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